



DA2JF2300L

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Small reverse current IR
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: 4A

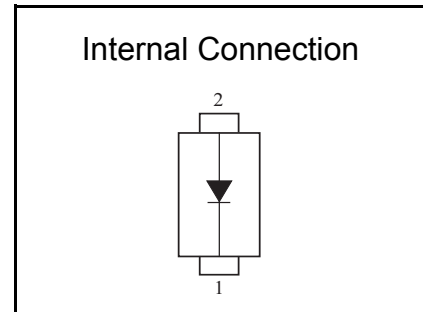
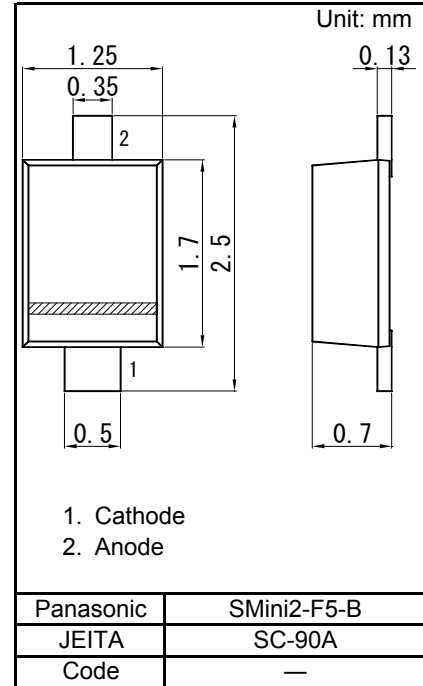
■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	VRRM	300	V
Non-repetitive peak reverse surge voltage	VRSM	300	V
Forward current (Average) ^{*1}	IF(AV)	0.3	A
Non-repetitive peak forward surge current ^{*2}	IFSM	3.0	A
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-40 to +150	°C

Note) *1: temperature:Ta = 90°C, with DC wave and
 Alumina PC board (Board :20 mm×50 mm, Soldering land:2 mm×2 mm)
 *2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

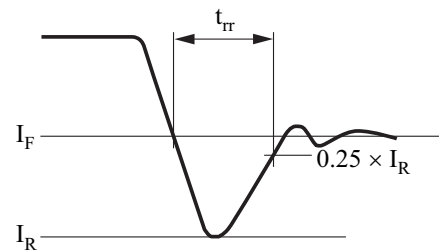
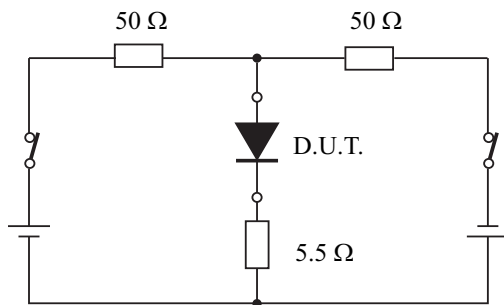




■ Electrical Characteristics Ta = 25 °C ± 3 °C

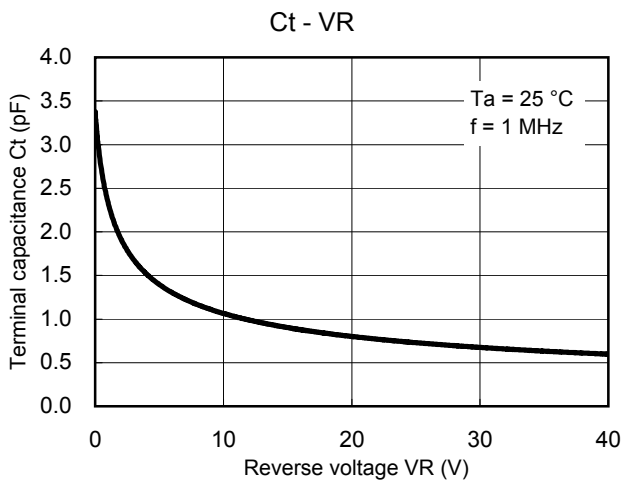
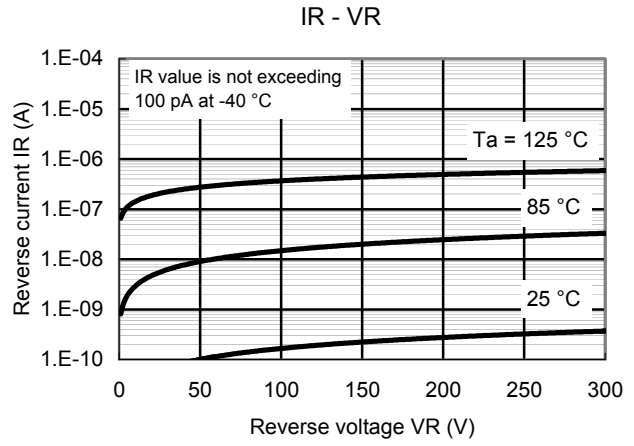
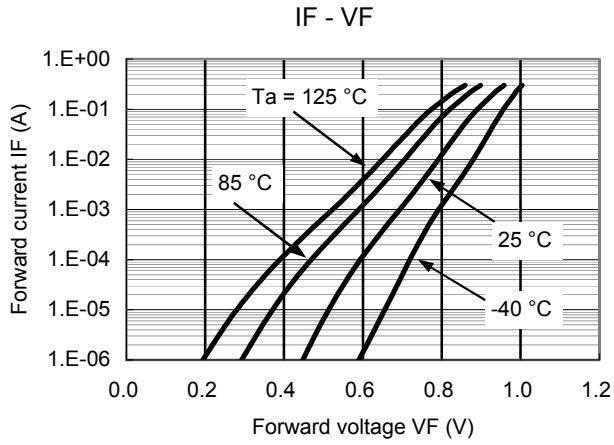
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 300 mA			1.25	V
Reverse current	IRRM	VRRM = 300 V			1.0	μA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		3.5		pF
Reverse recovery time *1	trr	IF = 100 mA, IR = 200mA Irr = 0.25 x IR		400		ns
Thermal resistance(ch-a) *2	Rth(j-a)	Mounted on an alumina PC board		160		°C/W

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 3. Absolute frequency of Input and output is 20 MHz
 4. *1 trr measurement circuit



*2 Mounted on an alumina PC board (Board: 20 mm×50 mm, Soldering land: 2 mm×2 mm)

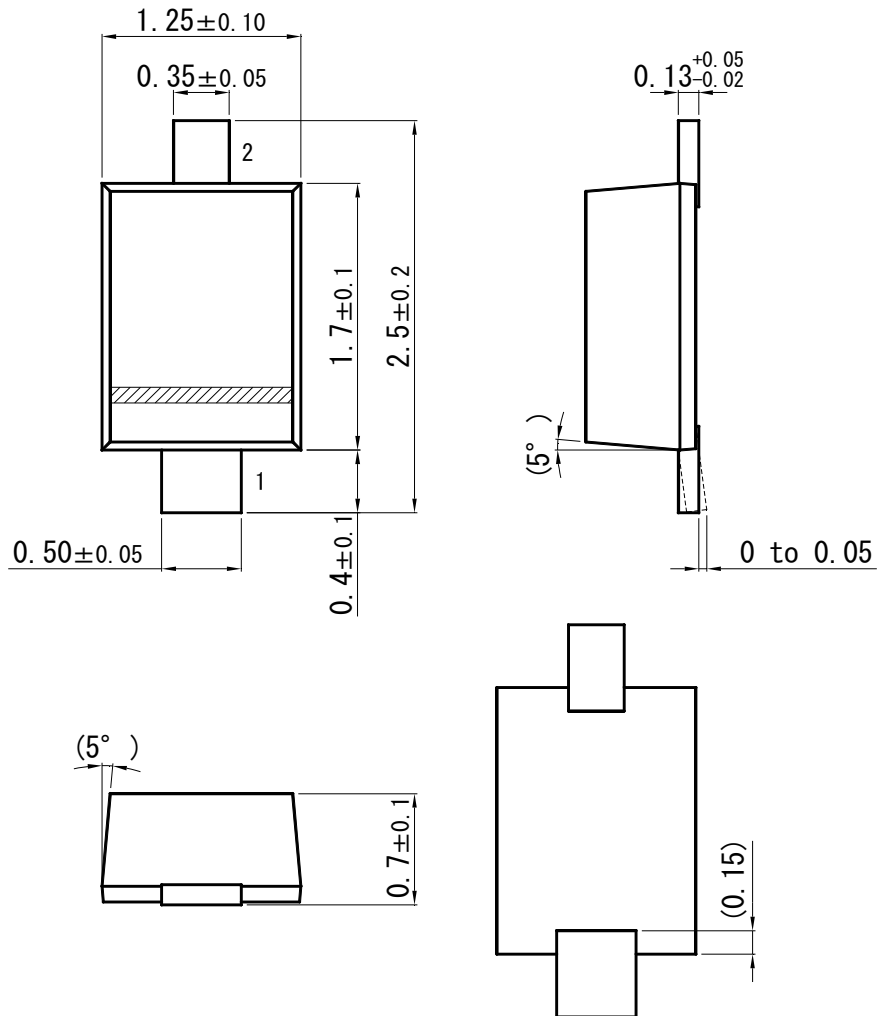
Technical Data (reference)



Panasonic

SMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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